3.0 A, Dual-Rail Very Low-Dropout Linear Regulator with Programmable Soft-Start

The NCP59744 is dual—rail very low dropout voltage regulator that is capable of providing an output current in excess of 3.0 A with a dropout voltage of 115 mV typ. at full load current. The devices are stable with ceramic and other low ESR output capacitors. This series contains adjustable output voltage version with output voltage down to 0.8 V. Internal protection features consist of built—in thermal shutdown and output current limiting protection. User—programmable Soft—Start and Power Good pins are available. The NCP59744 is available in QFN20—5x5—0.65P package.

Features

- Output Current in Excess of 3.0 A
- 0.25% Typical Accuracy Over Line and Load
- V_{IN} Range: 0.8 V to 5.5 V
- V_{BIAS} Range: 2.2 V to 5.5 V
- Output Voltage Range: 0.8 V to 3.6 V
- Dropout Voltage: 115 mV at 3 A
- Programmable Soft Start
- Open Drain Power Good Output
- Excellent Transient Response
- Current Limit and Thermal Shutdown Protection
- These are Pb-Free Devices

Applications

- Telecom and Industrial Equipment Point of Load Regulation
- FPGA, DSP and Logic Power Supplies
- Switching Power Supply Post Regulation
- Applications with Specific Start-up Time or Sequencing Requirements

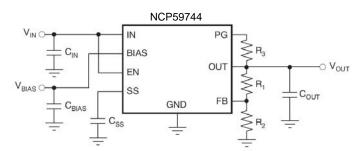


Figure 1. Typical Application Schematic



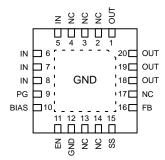
ON Semiconductor®

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QFN20 CASE 485DB

PIN CONNECTIONS



QFN20, 5x5, 0.65P

MARKING DIAGRAM



QFN20

A = Assembly Location

I /WI = Wafer I of

L/WL = Wafer Lot Y/YY = Year

W/WW = Work Week ■ Pb–Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 9 of this data sheet.

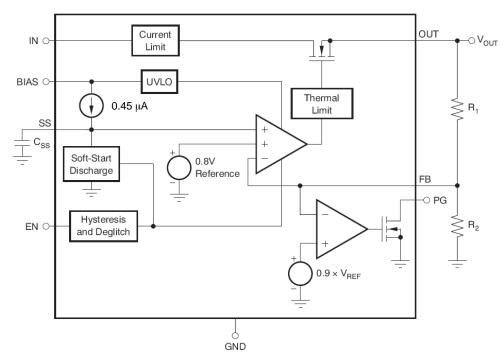


Figure 2. Simplified Schematic Block Diagram

Table 1. PIN FUNCTION DESCRIPTION

Name	QFN-20	Description
IN	5–8	Unregulated input to the device.
EN	11	Enable pin. Driving this pin high enables the regulator. Driving this pin low puts the regulator into shutdown mode. This pin must not be left floating.
SS	15	Soft–Start pin. A capacitor connected on this pin to ground sets the start–up time. If this pin is left floating, the regulator output soft–start ramp time is typically 200 μs.
BIAS	10	Bias input voltage for error amplifier, reference, and internal control circuits.
PG	9	Power–Good (PG) is an open–drain, active–high output that indicates the status of V_{OUT} . When V_{OUT} exceeds the PG trip threshold, the PG pin goes into a high–impedance state. When V_{OUT} is below this threshold the pin is driven to a low–impedance state. A pull–up resistor from 10 k Ω to 1 M Ω should be connected from this pin to a supply up to 5.5 V. The supply can be higher than the input voltage. Alternatively, the PG pin can be left floating if output monitoring is not necessary.
FB	16	This pin is the feedback connection to the center tap of an external resistor divider network that sets the output voltage. This pin must not be left floating.
OUT	1, 18–20	Regulated output voltage. It is recommended that the output capacitor ≥ 2.2 μF.
NC	2–4, 13, 14, 17	No connection. This pin can be left floating or connected to GND to allow better thermal contact to the top-side plane.
GND	12	Ground
PAD/TAB		Should be soldered to the ground plane for increased thermal performance

Table 2. ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Input Voltage Range	V _{IN}	-0.3 to +6	V
Input Voltage Range	V _{BIAS}	-0.3 to +6	V
Enable Voltage Range	V _{EN}	-0.3 to +6	V
Power-Good Voltage Range	V _{PG}	-0.3 to +6	V
PG Sink Current	I _{PG}	0 to +1.5	mA
SS Pin Voltage Range	V _{SS}	-0.3 to +6	V
Feedback Pin Voltage Range	V _{FB}	-0.3 to +6	V
Output Voltage Range	V _{OUT}	-0.3 to $(V_{IN} + 0.3) \le 6$	V
Maximum Output Current	I _{OUT}	Internally Limited	
Output Short Circuit Duration		Indefinite	
Continuous Total Power Dissipation	P _D	See Thermal Characteristics Table and Formula	
Maximum Junction Temperature	T _{JMAX}	+150	°C
Storage Junction Temperature Range	T _{STG}	-55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. Refer to ELECTRICAL CHĂRACTERISTICS and APPLICATION INFORMATION for Safe Operating Area.
- 2. This device series incorporates ESD protection and is tested by the following methods:
 - ESD Human Body Model tested per EIA/JESD22-A114
 - ESD Machine Model tested per EIA/JESD22-A115
 - Latch-up Current Maximum Rating tested per JEDEC standard: JESD78.

Table 3. THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal Characteristics, QFN20, 5x5, 0.65P package			
Thermal Resistance, Junction-to-Ambient (Note 5)	$R_{ heta JA}$	35.4	°C/W
Thermal Resistance, Junction-to-Board (Note 6)	$R_{\theta JB}$	14.7	°C/W
Thermal Resistance, Junction-to-Case (bottom) (Note 7)	$R_{ heta JC}$	3.9	°C/W

- 3. Refer to ELECTRICAL CHARACTERISTICS and APPLICATION INFORMATION for Safe Operating Area.
- 4. Thermal data are derived by thermal simulations based on methodology specified in the JEDEC JESD51 series standards. The following assumptions are used in the simulations:
 - These data were generated with only a single device at the center of a high–K (2s2p) board with 3 in x 3 in copper area which follows the JEDEC51.7 guidelines. Top and Bottom layer 2 oz. copper, inner planes 1 oz. copper.
 - The exposed pad is connected to the PCB ground inner layer through a 4x4 thermal via array. Vias are 0.3 mm diameter, plated.
 - Each of top and bottom copper layers has a dedicated pattern for 20% copper coverage.
- 5. The junction-to-ambient thermal resistance under natural convection is obtained in a simulation on a high-K board, following the JEDEC51.7 guidelines with assumptions as above, in an environment described in JESD51-2a.
 6. The junction-to-board thermal resistance is simulated in an environment with a ring cold plate fixture to control the PCB temperature, as
- The junction-to-board thermal resistance is simulated in an environment with a ring cold plate fixture to control the PCB temperature, as described in JESD51-8.
- 7. The junction–to–case (bottom) thermal resistance is obtained by simulating a cold plate test on the IC exposed pad. Test description can be found in the ANSI SEMI standard G30–88.

Table 4. RECOMMENDED OPERATING CONDITIONS (Note 8)

Rating	Symbol	Min	Max	Unit
Input Voltage	V _{IN}	V _{OUT} + V _{DO}	5.5	V
Bias Voltage	V _{BIAS}	2.2	5.5	V
Junction Temperature	TJ	-40	125	°C

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

8. Refer to ELECTRICAL CHARACTERISTICS and APPLICATION INFORMATION for Safe Operating Area.

Table 5. ELECTRICAL CHARACTERISTICS

(At V_{EN} = 1.1 V, V_{IN} = V_{OUT} + 0.3 V, C_{BIAS} = C_{IN} = 0.1 μ F, C_{OUT} = 10 μ F, I_{OUT} = 50 mA, V_{BIAS} = 5.0 V, T_J = -40°C to +125°C, unless otherwise noted. Typical values are at T_J = +25°C.)

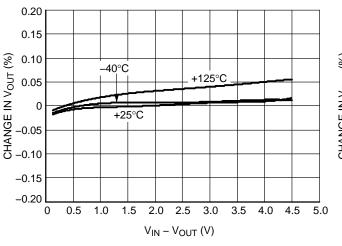
Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
V _{IN}	Input voltage range		V _{OUT} +V _{DO}		5.5	V
V _{BIAS}	Bias pin voltage range		2.2		5.5	V
UVLO	Undervoltage Lock-out	V _{BIAS} Rising Hysteresis	1.2	1.6 0.4	1.9 -	V
V _{REF}	Internal reference (Adj.)	T _J = +25°C	0.796	0.8	0.804	V
V _{OUT}	Output voltage range	V _{IN} = 5 V, I _{OUT} = 1.5 A, V _{BIAS} = 5 V	V _{REF}		3.6	V
Accuracy (Note 1)		$ \begin{array}{c} 2.97 \text{ V} \leq \text{V}_{\text{BIAS}} \leq 5.25 \text{ V}, \text{V}_{\text{OUT}} + \\ 1.62 \text{ V} \leq \text{V}_{\text{BIAS}} \\ 50 \text{ mA} \leq \text{I}_{\text{OUT}} \leq 3.0 \text{ A} \end{array} $	-1.0	±0.25	+1.0	%
V_{OUT}/V_{IN}	Line regulation	$V_{OUT(NOM)} + 0.3 \le V_{IN} \le 5.5 \text{ V}$		0.0006		%/V
V_{OUT}/I_{OUT}	Load regulation	$0 \text{ mA} \le I_{OUT} \le 50 \text{ mA}$		0.005		%/mA
		$50 \text{ mA} \le I_{OUT} \le 3.0 \text{ A}$		0.01		%/A
V_{DO}	V _{IN} dropout voltage (Note 2)	$I_{OUT} = 3.0 \text{ A},$ $V_{BIAS} - V_{OUT(NOM)} \ge 1.62 \text{ V}$		115	195	mV
	V _{BIAS} dropout voltage (Note 2)	$I_{OUT} = 3.0 \text{ A}, V_{IN} = V_{BIAS}$		1.13	1.5	V
I _{CL}	Current limit	$V_{OUT} = 80\% \times V_{OUT(NOM)}$	3.8	4.6	6	Α
I _{BIAS}	Bias pin current	$0 \text{ mA} \le I_{OUT} \le 3.0 \text{ A}$		1.3	2	mA
I _{SHDN}	Shutdown supply current	V _{EN} ≤ 0.4 V		1	10	μΑ
I _{FB}	Feedback pin current	$0 \text{ mA} \le I_{OUT} \le 3.0 \text{ A}$	-250	95	250	nA
PSRR	Power–supply rejection (V _{IN} to V _{OUT})	1 kHz, I _{OUT} = 1.5 A, V _{IN} = 1.8 V, V _{OUT} = 1.5 V		72		dB
		1 MHz, I _{OUT} = 1.5 A, V _{IN} = 1.8 V, V _{OUT} = 1.5 V		50		
	Power-supply rejection (V _{BIAS} to V _{OUT})	1 kHz, I _{OUT} = 1.5 A, V _{IN} = 1.8 V, V _{OUT} = 1.5 V		80		dB
		1 MHz, I _{OUT} = 1.5 A, V _{IN} = 1.8 V, V _{OUT} = 1.5 V		48		
Noise	Output noise voltage	100 Hz to 100 kHz, I _{OUT} = 3 A C _{ss} = 1.0 nF		18 x V _{OUT}		μVrms
V_{TRAN}	%V _{OUT} droop during load transient	I_{OUT} = 50 mA to 3.0 A at 1 A/µs, C_{OUT} = 10 µF, V_{OUT} = 3.3 V		±1.5		%V _{OUT}
t _{STRT}	Minimum startup time	I _{OUT} = 1.5 A, C _{SS} = open		200		μs
I _{SS}	Soft-start charging current	V _{SS} = 0.4 V		0.45		μΑ
V _{EN} , HI	Enable input high level		1.1		5.5	V
V _{EN} , LO	Enable input low level		0		0.4	V
V _{EN} ,HYS	Enable pin hysteresis			100		mV
$V_{EN,DG}$	Enable pin deglitch time			20		μs
I _{EN}	Enable pin current	V _{EN} = 5 V		0.3	1	μΑ
V _{IT}	PG trip threshold	V _{OUT} decreasing	86.5	90	93.5	%V _{OUT}
V _{HYS}	PG trip hysteresis			3		%V _{OUT}
V _{PG} , LO	PG output low voltage	I _{PG} = 1 mA (sinking), V _{OUT} < V _{IT}			0.3	V
I _{PG} , LKG	PG leakage current	V _{PG} = 5.25 V, V _{OUT} > V _{IT}		0.03	1	μΑ
TSD	Thermal shutdown temperature	Shutdown, temperature increasing Reset, temperature decreasing		+165 +140		°C

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

Adjustable devices tested at 0.8 V; external resistor tolerance is not taken into account.
 Dropout is defined as the voltage from the input to V_{OUT} when V_{OUT} is 2% below nominal.

TYPICAL CHARACTERISTICS

At T_J = +25°C, V_{OUT} = 1.5 V, V_{IN} = V_{OUT(TYP)} + 0.3 V, V_{BIAS} = 3.3 V, I_{OUT} = 50 mA, V_{EN} = V_{IN}, C_{IN} = 1 μ F, C_{BIAS} = 1 μ F, C_{SS} = 0.01 μ F, and C_{OUT} = 10 μ F, unless otherwise noted.



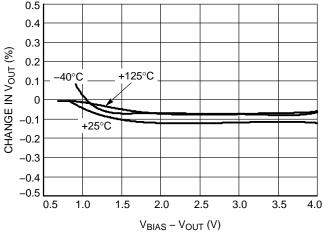
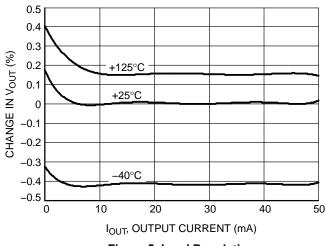


Figure 3. V_{IN} Line Regulation

Figure 4. V_{BIAS} Line Regulation



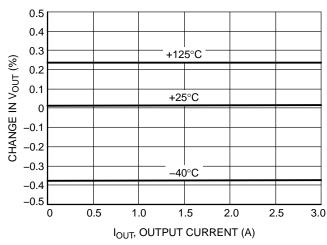
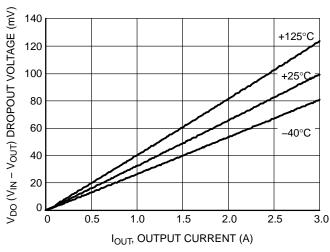


Figure 5. Load Regulation

Figure 6. Load Regulation



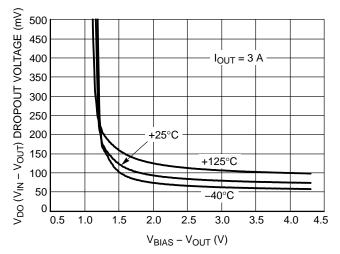
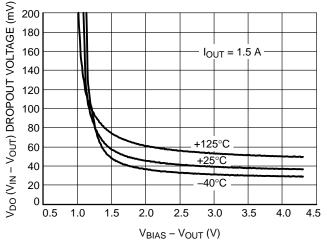


Figure 7. V_{IN} Dropout Voltage vs. I_{OUT} and Temperature T_J

Figure 8. V_{IN} Dropout Voltage vs. (V_{BIAS} – V_{OUT}) and Temperature T_J

TYPICAL CHARACTERISTICS

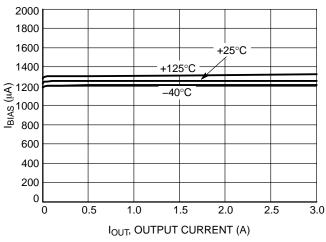
At T_J = +25°C, V_{OUT} = 1.5 V, V_{IN} = V_{OUT(TYP)} + 0.3 V, V_{BIAS} = 3.3 V, I_{OUT} = 50 mA, V_{EN} = V_{IN}, C_{IN} = 1 μ F, C_{BIAS} = 1 μ F, C_{SS} = 0.01 μ F, and C_{OUT} = 10 μ F, unless otherwise noted.



E 1400 B 1300 1100 OD 1000 OD 1000

Figure 9. V_{IN} Dropout Voltage vs. (V_{BIAS} – V_{OUT}) and Temperature T_J

Figure 10. V_{BIAS} Dropout Voltage vs. I_{OUT} and Temperature T_J



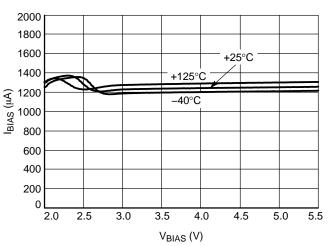
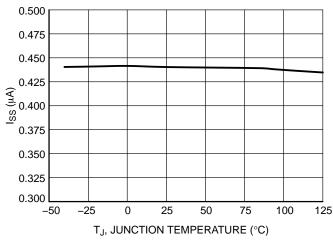


Figure 11. BIAS Pin Current vs. I_{OUT} and Temperature T_{.I}

Figure 12. BIAS Pin Current vs. V_{BIAS} and Temperature T_J



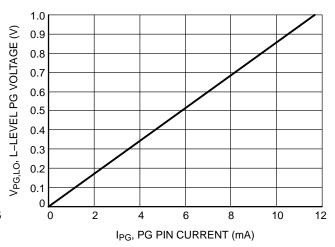


Figure 13. Soft Start Charging Current I_{SS} vs. Temperature T_J

Figure 14. L-level PG Voltage vs. Current

TYPICAL CHARACTERISTICS

At T_J = +25°C, V_{OUT} = 1.5 V, V_{IN} = V_{OUT(TYP)} + 0.3 V, V_{BIAS} = 3.3 V, I_{OUT} = 50 mA, V_{EN} = V_{IN}, C_{IN} = 1 μ F, C_{BIAS} = 1 μ F, C_{SS} = 0.01 μ F, and C_{OUT} = 10 μ F, unless otherwise noted.

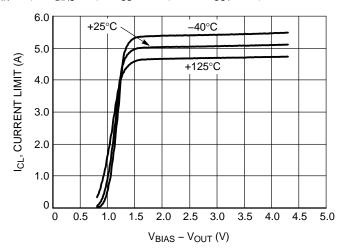


Figure 15. Current Limit vs. ($V_{BIAS} - V_{OUT}$)

APPLICATIONS INFORMATION

The NCP59744 dual–rail very low dropout voltage regulator is using NMOS pass transistor for output voltage regulation from $V_{\rm IN}$ voltage. All the low current internal controll circuitry is powered from the $V_{\rm BIAS}$ voltage.

The use of an NMOS pass transistor offers several advantages in applications. Unlike a PMOS topology devices, the output capacitor has reduced impact on loop stability. Vin to Vout operating voltage difference can be very low compared with standard PMOS regulators in very low Vin applications.

The NCP59744 offers programmable smooth monotonic start-up. The controlled voltage rising limits the inrush current what is advantageous in applications with large capacitive loads. The Voltage Controlled Soft Start timing is programmable by external Css capacitor value.

The Enable (EN) input is equipped with internal hysteresis and deglitch filter.

Open Drain type Power Good (PG) output is available for Vout monitoring and sequencing of other devices.

NCP59744 is a Adjustable linear regulator. The required Output voltage can be adjusted by two external resistors. Typical application schematics is shown in Figure 16.

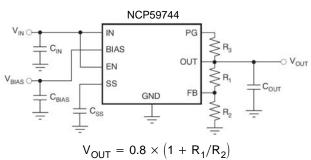


Figure 16. Typical Application Schematics

Dropout Voltage

Because of two power supply inputs V_{IN} and V_{BIAS} and one V_{OUT} regulator output, there are two Dropout voltages specified.

The first, the V_{IN} Dropout voltage is the voltage difference ($V_{IN}-V_{OUT}$) when V_{OUT} starts to decrease by percents specified in the Electrical Characteristics table. V_{BIAS} is high enough, specific value is published in the Electrical Characteristics table.

The second, V_{BIAS} dropout voltage is the voltage difference ($V_{BIAS} - V_{OUT}$) when V_{IN} and V_{BIAS} pins are joined together and V_{OUT} starts to decrease.

Input and Output Capacitors

The device is designed to be stable for all available types and values of output capacitors $\geq 2.2 \,\mu\text{F}$. The device is also stable with multiple capacitors in parallel, which can be of any type or value.

In applications where low input supply impedance is available (PCB inductance on Vin and/or Vbias as an example) the recommended Cin and Cbias value is 1 µF or

greater. In order to avoid any excessive input voltage transients caused i.e. by a sudden output short circuit conditions the input capacitor value should be sized properly for each particular application to counteract any input inductance. For Vin of 5.5 V the recommended input capacitance is 22 μF or greater. Ceramic or other low ESR capacitors are recommended. For the best performance all capacitors should be connected to the NCP59744 respective pins directly in the device PCB copper layer, not through vias having not negligible impedance.

Enable Operation

The enable pin will turn the regulator on or off. The threshold limits are covered in the electrical characteristics table in this data sheet. If the enable function is not to be used then the pin should be connected to $V_{\rm IN}$ or $V_{\rm BIAS}$.

Output Noise

When the NCP59744 device reaches the end of the Soft–Start cycle, the Soft Start capacitor is switched to serve as a Noise filtering capacitor.

Output Voltage Adjust

The output voltage can be adjusted from 0.8 V to 3.6 V using resistors divider between the output and the FB input. Recommended resistor values for frequently used voltages can be found in the Table 6.

Programmable Soft-Start

The Soft-Start ramp time depends on the Soft Start charging current I_{SS} , Soft-Start capacitor value C_{SS} and internal reference voltage V_{REF} .

The Soft –Start time can be calculated using following equations:

 $t_{ss} = C_{SS} x (V_{REF} / I_{SS}) [s, F, V, A]$

or in more practical units

 $t_{SS} = C_{SS} \times 0.8 \text{V} / 0.44 = C_{SS} \times 1.82$

where

 $t_{ss} = Soft-Start time in miliseconds$

 $C_{SS} = Soft-Start$ capacitor value in nano Farads

Capacitor values for frequently used Soft-Start times can be found in the Table 7.

The maximal recommended value of C_{SS} capacitor is 15 nF. For higher C_{SS} values the capacitor full discharging before new Soft-Start cycle is not guaranteed.

Current Limitation

The internal Current Limitation circuitry allows the device to supply the full nominal current and surges but protects the device against Current Overload or Short.

Thermal Protection

Internal thermal shutdown (TSD) circuitry is provided to protect the integrated circuit in the event that the maximum junction temperature is exceeded. When TSD activated , the regulator output turns off. When cooling down under the low

temperature threshold, device output is activated again. This TSD feature is provided to prevent failures from accidental overheating.

Table 6. RESISTOR VALUES FOR PROGRAMMING THE OUTPUT VOLTAGE

V _{OUT} (V)	R ₁ (kΩ)	R_2 (k Ω)
0.8	Short	Open
0.9	0.619	4.99
1.0	1.13	4.53
1.05	1.37	4.33
1.1	1.87	4.99
1.2	2.49	4.99
1.5	4.12	4.75
1.8	3.57	2.87
2.5	3.57	1.69
3.3	3.57	1.15

NOTE: $V_{OUT} = 0.8 \times (1 + R_1/R_2)$

Resistors in the table are standard 1% types

Table 7. CAPACITOR VALUES FOR PROGRAMMING THE SOFT-START TIME

Soft-Start Time	C _{SS}		
0.2 ms	Open		
0.5 ms	270 pF		
1 ms	560 pF		
5 ms	2.7 nF		
10 ms	5.6 nF		
18 ms	10 nF		

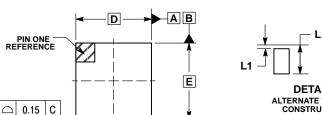
Table 8. ORDERING INFORMATION

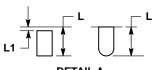
Device	Output Current	Output Volt- age	Junction Temp. Range	Package	Shipping [†]
NCP59744MN2ADJTBG	3.0 A	ADJ	-40°C to +125°C	QFN20 (Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

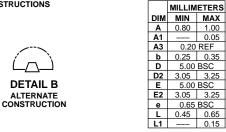
PACKAGE DIMENSIONS

QFN20 5x5, 0.65P CASE 485DB **ISSUE O**





DETAIL A ALTERNATE TERMINAL CONSTRUCTIONS



NOTES

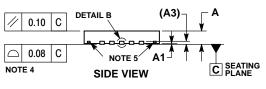
 DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS.

PAD AS WELL AS THE TERMINALS.

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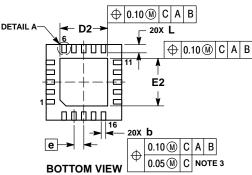
OPTIONAL FEATURES

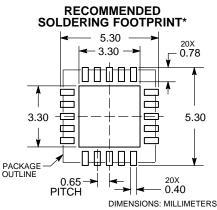
DIMENSION b APPLIES TO PLATED
TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM THE TERMINAL TIP.
COPLANARITY APPLIES TO THE EXPOSED



TOP VIEW

0.15 С





*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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